SDLS145A-APRIL 1985-REVISED JULY 2008



# **QUADRUPLE BUS TRANSCEIVERS**

#### **FEATURES**

- Two-Way Asynchronous Communication Between Data Buses
- PNP Inputs Reduce D-C Loading
- Hysteresis (Typically 400 mV) at Inputs Improves Noise Margin

SN54LS243 . . . J OR W PACKAGE SN74LS243 . . . D, N, OR NS PACKAGE (TOP VIEW)

1	<u></u> 14	□ v <sub>cc</sub>
2	13	GBA
3	12	NC
4	11	☐ B1
5	10	☐ B2
6	9	☐ B3
7	8	☐ B4
	3 4 5	2 13 3 12 4 11 5 10

# FUNCTION TABLE (EACH TRANSCEIVER)

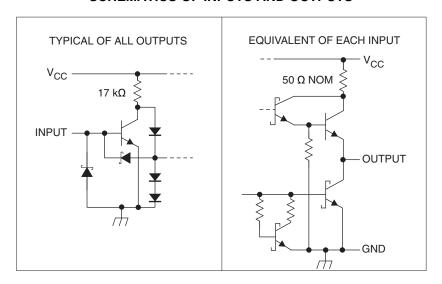
INP	UTS	Chlynd C242
GAB	GBA	SNxxLS243
L	L	A to B
Н	Н	B to A
Н	L	Isolation
L	Н	Latch A and B (A = B)

#### DESCRIPTION

These four-data-line transceivers are designed for asynchronous two-way communications between data buses. SN74LS243 can be used to drive terminated lines down to  $133~\Omega$ .

SN54LS243 is characterized for operation over the full military temperature range of -55°C to 125°C. SN74LS243 is characterized for operation from 0°C to 70°C.

#### **SCHEMATICS OF INPUTS AND OUTPUTS**

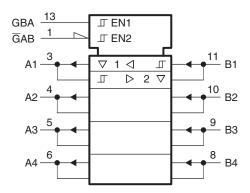




Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

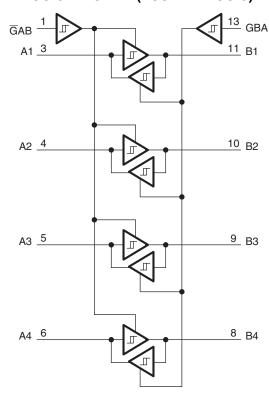


### **LOGIC SYMBOL**



A. These symbols are in accordance with ANSI/EEE Std. 91-1984 and IEC Publication 617-12.

### **LOGIC DIAGRAM (POSITIVE LOGIC)**





### **ABSOLUTE MAXIMUM RATINGS**(1)

			MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage <sup>(2)</sup>			7	V	
V <sub>IN</sub>	Input voltage	Input voltage				
	OFF-state output voltage		5.5	V		
_		SN54LS243	-55	125	00	
T <sub>A</sub>	Operating free-air temperature range	SN74LS243	0	70	°C	
T <sub>stg</sub>	Storage temperature range		-65	150	°C	

<sup>(1)</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		SNS	54LS243		SN7	UNIT			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
$V_{CC}$	Supply voltage <sup>(1)</sup>	4.5	5	5.5	4.75	5	5.25	V	
V <sub>IH</sub>	High-level input voltage	2			2			V	
V <sub>IL</sub>	Low-level input voltage			0.7			0.8	V	
I <sub>OH</sub>	High-level output voltage			-12			-15	mA	
I <sub>OL</sub>	Low-level output voltage			12			24	mA	
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C	

<sup>(1)</sup> Voltage values are with respect to network ground terminal.

<sup>(2)</sup> Voltage values are with respect to network ground terminal.



#### **ELECTRICAL CHARACTERISTICS**

over operating free-air temperature range (unless otherwise noted)

	DADAMETED	-	TOT CONDITI	ONC(1)	SN5	4LS243		SN	174LS243	3	LINUT
	PARAMETER	'	EST CONDITI	ON5(")	MIN	TYP <sup>(2)</sup>	MAX	MIN	TYP <sup>(2)</sup>	MAX	UNIT
V <sub>IK</sub>	A or B	V <sub>CC</sub> = MIN,	$I_1 = -18 \text{ mA}$				-1.5			-1.5	V
Hystere	esis (V <sub>T+</sub> – V <sub>T-</sub> )	$V_{CC} = MIN,$			0.2	0.4		0.2	0.4		V
V		V MINI	V 2.V	$V_{IL} = MAX,$ $I_{OH} = -3 \text{ mA}$	2.4	3.1		2.4	3.1		V
V <sub>OH</sub>		$V_{CC} = MIN,$	ν <sub>IH</sub> = 2 ν,	$V_{IL} = 0.5 \text{ V},$ $I_{OH} = \text{MAX}$	2			2			
\/		$V_{CC} = MIN,$	$V_{IH} = 2 V$ ,	$I_{OL} = 12 \text{ mA}$		0.25	0.4		0.25	0.4	V
V <sub>OL</sub>	$V_{IL} = MAX$			$I_{OL} = 24 \text{ mA}$					0.35	0.5	V
I <sub>OZH</sub>		$V_{CC} = MIN,$ $V_{IL} = MAX,$	$V_{IH} = 2 V$ ,	$V_0 = 2.7 \text{ V}$			40			40	μΑ
I <sub>OZL</sub>		$V_{CC} = MIN,$ $V_{IL} = MAX,$	$V_{IH} = 2 V$ ,	$V_0 = 0.4 \text{ V}$			-200			-200	μΑ
	A or B	V MAY		V <sub>I</sub> = 5.5 V			0.1			0.1	A
I <sub>I</sub>	GAB or GBA	$V_{CC} = MAX,$		V <sub>I</sub> = 7 V			0.1			0.1	mA
I <sub>IH</sub>	·	V <sub>CC</sub> = MAX,					20			20	μΑ
	A inputs	V <sub>CC</sub> = MAX, GAB and GB	•				-0.2			-0.2	
I <sub>IL</sub>	B inputs	V <sub>CC</sub> = MAX, GAB and GB	•				-0.2			-0.2	mA
	GAB or GBA	$V_{CC} = MAX$ ,	$V_1 = 0.4 V$ ,				-0.2			-0.2	
Ios	-	V <sub>CC</sub> = MAX			-40		-225	-40		-225	mA
	Outputs high					22	38		22	38	
I <sub>CC</sub>	Outputs low	$V_{CC} = MAX,$	Outputs open	ı.		29	50		29	50	mA
.00	All outputs disabled	(5)	Carpato opon	,		32	54		32	54	

<sup>(1)</sup> For conditions shown as MIN or MAX, use the appropriate value specified under "recommended operating conditions."

### **SWITCHING CHARACTERISTICS**

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$ 

PARAMETER	TEST CO	SN5		SN7	UNIT				
PARAMETER	1231 60	NUTTIONS	MIN	TYP	MAX	MIN	TYP	MAX	Oitii
t <sub>PLH</sub>	D 667.0			9	14		12	18	ns
t <sub>PHL</sub>		C <sub>L</sub> = 45 pF		12	18		12	18	ns
t <sub>PZL</sub>	$R_L = 667 \Omega$ ,		OL = 45 pi		20	30		20	30
t <sub>PZH</sub>				15	23		15	23	ns
t <sub>PLZ</sub>	$R_1 = 667 \Omega$	C <sub>1</sub> = 5 pF		10	20		10	20	ns
t <sub>PHZ</sub>	N <sub>L</sub> = 007 12,	O <sub>L</sub> = 3 μr		15	25		15	25	ns

Submit Documentation Feedback

 <sup>(2)</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.
 (3) I<sub>CC</sub> is measured with transceivers eabled in one direction only, or with all transceivers disabled.

www.ti.com

11-Nov-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
8002002CA	Active	Production	CDIP (J)   14			N/A for Pkg Type	-55 to 125	8002002CA SNJ54LS243J	
8002002DA	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8002002DA SNJ54LS243W
SN54LS243J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS243J
SN54LS243J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS243J
SN74LS243D	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	0 to 70	LS243
SN74LS243DR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS243
SN74LS243DR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS243
SN74LS243N	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS243N
SN74LS243N.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS243N
SN74LS243NE4	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS243N
SNJ54LS243J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8002002CA SNJ54LS243J
SNJ54LS243J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8002002CA SNJ54LS243J
SNJ54LS243W	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type -55 to 125		8002002DA SNJ54LS243W
SNJ54LS243W.A	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8002002DA SNJ54LS243W

<sup>(1)</sup> **Status:** For more details on status, see our product life cycle.

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

### **PACKAGE OPTION ADDENDUM**

www.ti.com 11-Nov-2025

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54LS243, SN74LS243:

Catalog: SN74LS243

Military: SN54LS243

NOTE: Qualified Version Definitions:

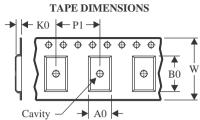
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 24-Jul-2025

### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

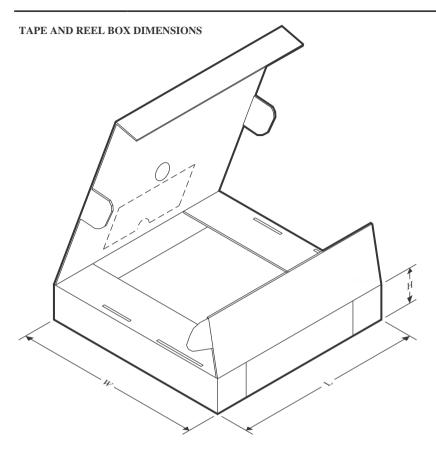


#### \*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS243DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

www.ti.com 24-Jul-2025



#### \*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
I	SN74LS243DR	SOIC	D	14	2500	353.0	353.0	32.0

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 24-Jul-2025

### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
8002002DA	W	CFP	14	25	506.98	26.16	6220	NA
SN74LS243N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS243N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS243N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS243N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS243NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS243NE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS243W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54LS243W.A	W	CFP	14	25	506.98	26.16	6220	NA



SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



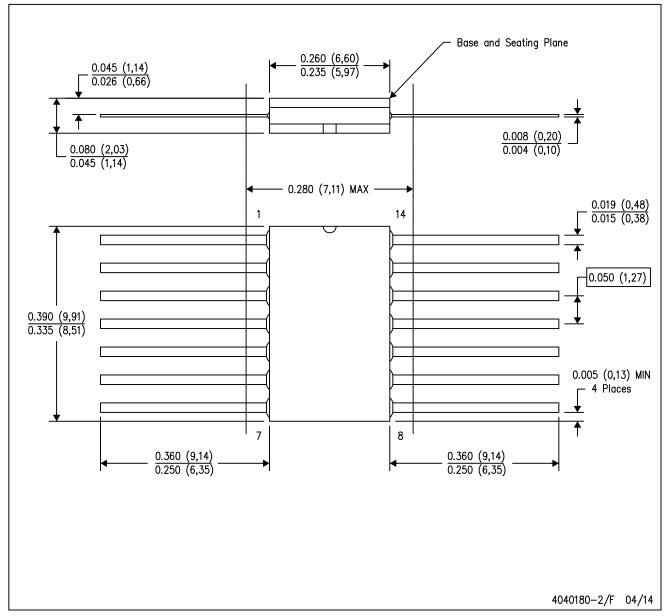
NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



# W (R-GDFP-F14)

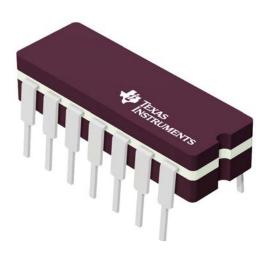
# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



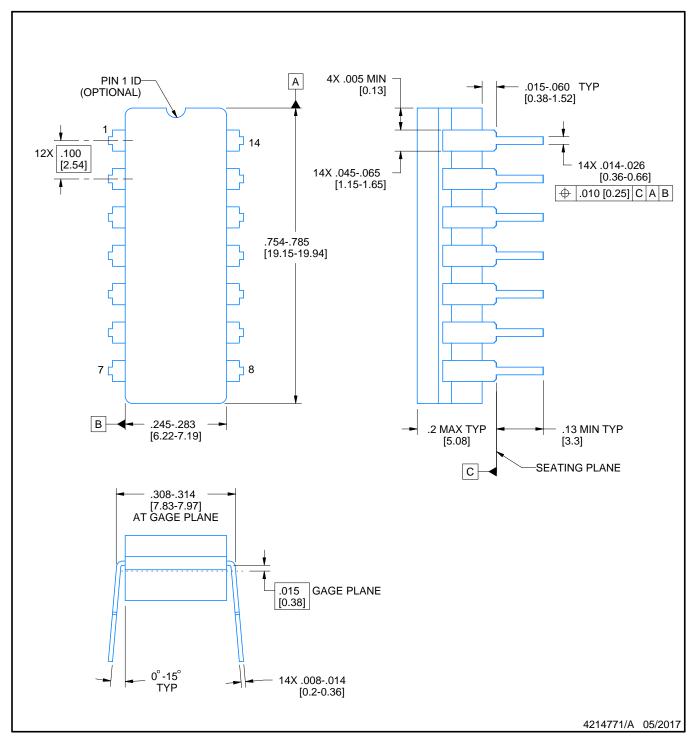
Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





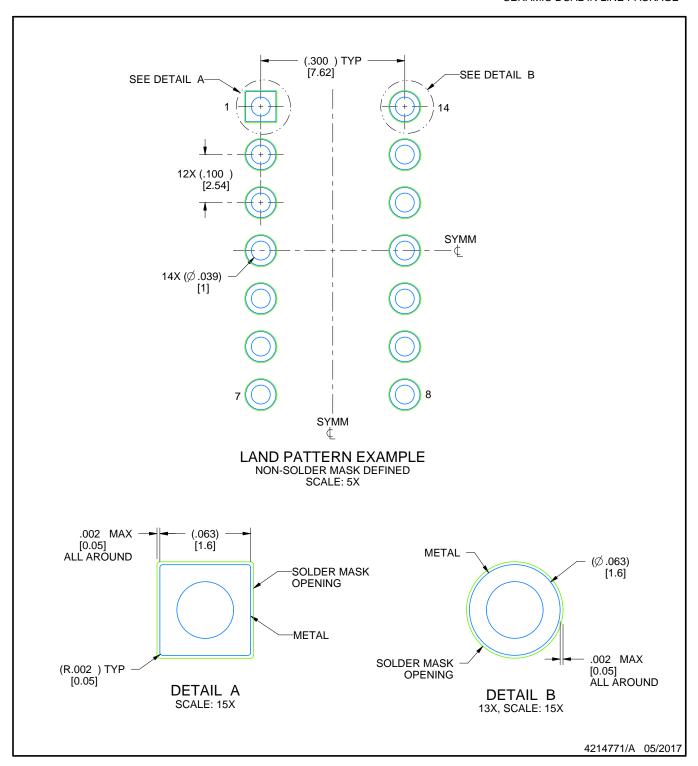
CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



#### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025